

A post chemical-mechanical-polishing (post-CMP) cleaning composition comprising a specific sulfur-containing compound and a sugar alcohol or a polycarboxylic acid

5

Abstract

A post chemical-mechanical-polishing (post-CMP) cleaning composition comprising: (A) at least one compound comprising at least one thiol ($-\text{SH}$), thioether ($-\text{SR}^1$) or thiocarbonyl ($>\text{C}=\text{S}$) group, wherein R^1 is alkyl, aryl, alkylaryl or arylalkyl, (B) at least one sugar alcohol which contains at least three hydroxyl ($-\text{OH}$) groups and does not comprise any carboxylic acid ($-\text{COOH}$) or carboxylate ($-\text{COO}^-$) groups, and (C) an aqueous medium.

(No suitable figure)